

TROPHY SERIES

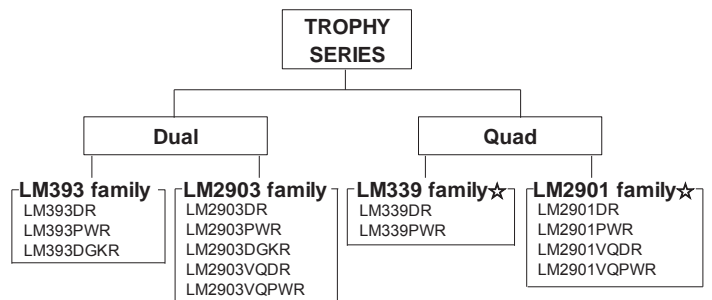


Universal Standard Ground Sense Comparator

LM393 family, LM339 family, LM2903 family, LM2901 family

●Description

The Universal Standard family LM393/LM339/LM2903/LM2901 monolithic ICs integrate two/four independent comparators on a single chip and feature high gain, low power consumption, and an operating voltage range from 2[V] to 36[V] (single power supply).

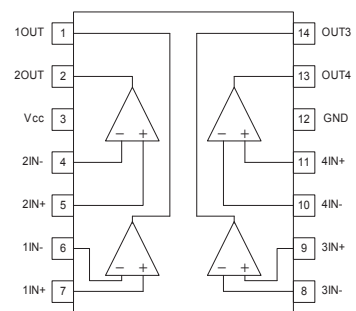
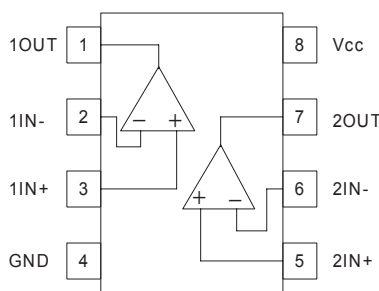


☆Under development

●Characteristics

- 1) Operating temperature range
Commercial Grade
LM339/393 family: 0[°C] to +70[°C]
Extended Industrial Grade
LM2903/2901 family: -40[°C] to +125[°C]
- 2) Open collector output
- 3) Single / dual power supply compatible
- 4) Low supply current
0.8[mA] typ. (LM393/339/2903/2901 family)
- 5) Low input-bias current : 25[nA] typ.
- 6) Low input-offset voltage: 2[mV] typ.
- 7) Differential input voltage range equal to maximum rating
- 8) Low output saturation voltage
- 9) TTL, MOS, CMOS compatible output

●Pin Assignment



☆Under development

SOIC8

LM393DR
LM2903DR
LM2903VQDR

TSSOP8

LM393PWR
LM2903PWR
LM2903VQPWR

MSOP8/VSSOP8

LM393DGKR
LM2903DGKR

SOIC14

LM339DR
LM2901DR
LM2901VQDR

TSSOP14

LM339PWR
LM2901PWR
LM2901VQPWR

● Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating				Unit
		LM393 family	LM339 family ☆	LM2903 family	LM2901 family ☆	
Supply Voltage	Vcc-GND	+36				V
Input Differential Voltage	Vid	±36				V
Common-mode Input	Vicm	-0.3 to +36				V
Operating Temperature	Topr	0 to +70		-40 to +125		°C
Storage Temperature Range	Tstg	-65 to +150				°C
Maximum Junction Temperature	Tj	+150				°C

☆ Under development

● Electric Characteristics

○ LM393/339 family (Unless otherwise specified, Vcc=+5[V])

Parameter	Symbol	Temperature range	Limit						Unit	condition	Fig.No.
			LM393 family			LM339 family ☆					
			Min.	Typ.	Max.	Min.	Typ.	Max.			
Input Offset Voltage (*1)	VIO	25°C	—	2	7	—	2	7	mV	Vcc=5 to 30[V], VO=1.4[V] VIC=VIC(min)	2
		Full range	—	—	9	—	—	9			
Input Offset Current (*1)	IIO	25°C	—	5	50	—	5	50	nA	VO=1.4[V]	2
		Full range	—	—	250	—	—	150			
Input Bias Current (*1)	IIB	25°C	—	25	250	—	25	250	nA	VO=1.4[V]	2
		Full range	—	—	400	—	—	400			
Common-mode Input Voltage Range	VICR	25°C	—	—	Vcc-1.5	—	—	Vcc-1.5	V	—	2
		Full range	—	—	Vcc-2.0	—	—	Vcc-2.0			
Large Signal Differential Voltage Amplification	AVD	25°C	25	200	—	25	200	—	V/mA	Vcc=15[V] VO=1.4 to 11.4[V], RL ≥ 15[kΩ], VRL=15[V]	2
High Level Output Current	IOH	25°C	—	0.1	—	—	0.1	—	nA	VID=1[V], VO=5[V]	3
		Full range	—	—	1	—	—	1	μA	VID=1[V], VO=30[V]	
Low Level Output Voltage	VOL	25°C	—	150	400	—	150	400	mV	VID=-1[V], IOL=4[mA]	3
		Full range	—	—	700	—	—	700			
Low Level Output Current	IOL	25°C	6	—	—	6	16	—	mA	VID=-1[V], VOL=1.5[V]	3
Supply Current	ICC	25°C	—	0.8	1	—	0.8	2	mA	RL=∞, Vcc=5V	3
		Full range	—	—	2.5	—	—	—		RL=∞, Vcc=30[V]	
Response Time	Tre	25°C	—	1.3	—	—	1.3	—	μs	RL=5.1[kΩ], VRL=5[V], CL=15pF VIN=100[mVp-p], overdrive=5[mV]	3
			—	0.3	—	—	0.3	—		RL=5.1[kΩ], VRL=5[V], CL=15pF VIN=TTL-Level input step Vref=1.4[V]	

(*1) Absolute value

☆ Under development

○LM2903/2901 family(Unless otherwise specified, Vcc=+5[V])

Parameter	Symbol	Temperature range	Limit						Unit	Condition	Fig.No.	
			LM2903 family			LM2901 family☆						
			Min.	Typ.	Max.	Min.	Typ.	Max.				
Input Offset Voltage (*2)	VIO	25°C	—	2	7	—	2	7	mV	Vcc=5 to MAX (*7), VO=1.4[V] VIC=VIC (min)	2	
		Full range	—	—	15	—	—	15				
Input Offset Current (*2)	IIO	25°C	—	5	50	—	5	50	nA	VO=1.4[V]	2	
		Full range	—	—	200	—	—	200				
Input Bias Current (*2)	IIB	25°C	—	25	250	—	25	250	nA	VO=1.4[V]	2	
		Full range	—	—	500	—	—	500				
Common-mode Input Voltage Range	VICR	25°C	—	—	Vcc-1.5	—	—	Vcc-1.5	V	—	2	
		Full range	—	—	Vcc-2.0	—	—	Vcc-2.0				
Large Signal Differential Voltage Amplification	AVD	25°C	25	100	—	25	100	—	V/mV	Vcc=15[V], VOUT=1.4 to 11.4[V], RL ≥ 15[kΩ], VRL=15[V]	2	
High Level Output Current	IOH	25°C	—	0.1	—	—	0.1	—	nA	VID=1[V], VOH=5[V]	3	
		Full range	—	—	1	—	—	1	μA	VID=1[V], VOH=MAX(*7)		
Low Level Output Voltage	LM2901(*3)	VOL	25°C	—	150	400	—	150	500	mV	VID=-1[V], IOL=4[mA]	3
	LM2901V(*3)		25°C	—	150	400	—	150	400			
	Full range		—	—	700	—	—	700				
Low Level Output Current	IOL	25°C	6	16	—	6	16	—	mA	VID=-1[V], VOL=1.5[V]	3	
Supply Current	ICC	25°C	—	0.8	2	—	0.8	2	mA	RL=∞, Vcc=5V	3	
			—	1	2.5	—	1	2.5		RL=∞, Vcc=MAX(*7)		
Response Time	Tre	25°C	—	1.3	—	—	1.3	—	μs	RL=5.1[Ω], VRL=5[V], CL=15pF VIN=100[mVp-p], Overdrive=5[mV]	3	
			—	0.3	—	—	0.3	—		RL=5.1[kΩ], VRL=5[V], CL=15pF VIN=TTL-Level input step Vref=1.4[V]		

(*2) Absolute value

☆Under development

(*3) Supply Voltage Maximum Value LM2901DR, LM2901PWR MAX=30[V], LM2901VQDR, LM2901VQPWR MAX=32[V]

● Circuit Diagram

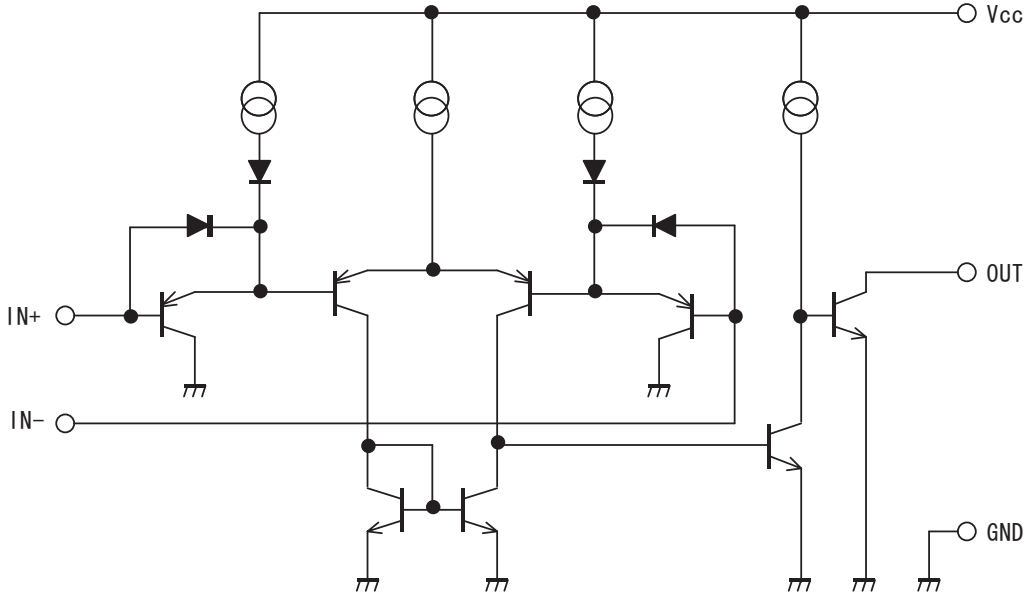


Fig.1 Circuit Diagram (each Comparator)

● Measurement circuit 1 NULL Method measurement condition

Vcc,GND,EK,VICR Unit : [V]

Parameter	VF	S1	S2	S3	LM393/LM339 family				LM2903/LM2901 family				Calculation
					Vcc	GND	EK	VICR	Vcc	GND	EK	VICR	
Input Offset Voltage	VF1	ON	ON	ON	5 to 30	0	-1.4	0	5 to 30	0	-1.4	0	1
Input Offset Current	VF2	OFF	OFF	ON	5	0	-1.4	0	5	0	-1.4	0	2
Input Bias Current	VF3	OFF	ON	ON	5	0	-1.4	0	5	0	-1.4	0	3
	VF4	ON	OFF		5	0	-1.4	0	5	0	-1.4	0	
Large Signal Voltage Gain	VF5	ON	ON	ON	15	0	-1.4	0	15	0	-1.4	0	4
	VF6				15	0	-11.4	0	15	0	-11.4	0	

— Calculation —

1. Input offset voltage (VIO)

$$V_{io} = \frac{|VF1|}{1 + R_f/R_s} [V]$$

2. Input offset current (IIO)

$$I_{io} = \frac{|VF2 - VF1|}{R_i(1 + R_f/R_s)} [A]$$

3. Input bias current (IIB)

$$I_b = \frac{|VF4 - VF3|}{2 \times R_i(1 + R_f/R_s)} [A]$$

4. Large signal differential voltage gain (AVD)

$$AV = 20 \times \text{Log} \frac{10 \times (1 + R_f/R_s)}{|VF6 - VF5|} [dB]$$

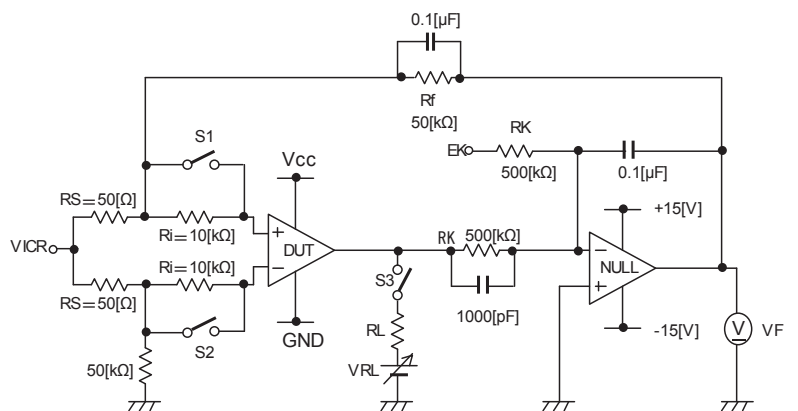


Fig.2 Measurement Circuit1 (each Comparator)

● Measurement Circuit2 Switch Condition

SW No.		SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7
Supply Current	—	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Low Level Output Current	VOL=1.5[V]	OFF	ON	ON	OFF	ON	ON	OFF
Low Level Output Current	IOL=4[mA]	OFF	ON	ON	OFF	OFF	OFF	ON
High Level Output Current	VOH=36[V]	OFF	ON	ON	OFF	OFF	OFF	ON
Response Time	RL=5.1[kΩ] VRL=5[V]	ON	OFF	ON	ON	OFF	ON	OFF

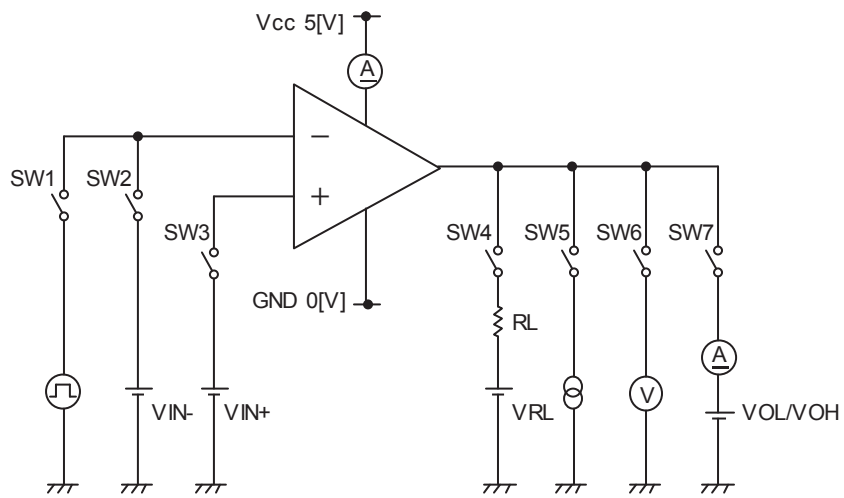


Fig.3 Measurement Circuit2 (each channel)

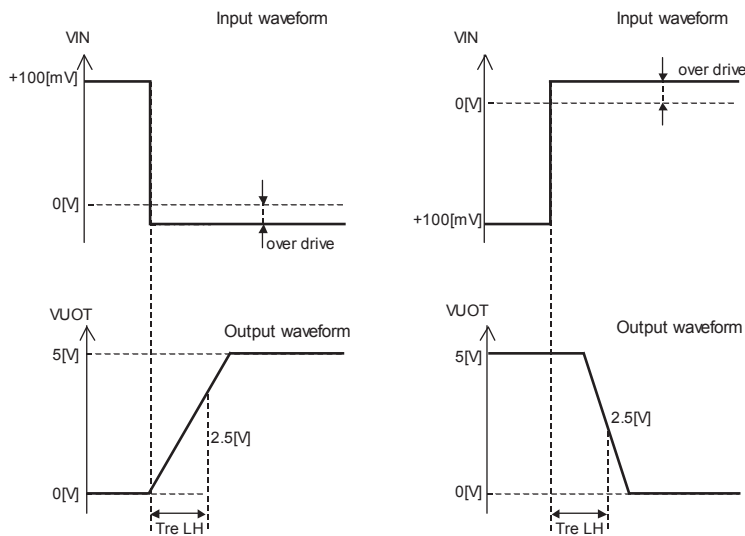


Fig.4 Response Time

● Description of Electrical Characteristics

Described below are descriptions of the relevant electrical terms.

Please note that item names, symbols, and their meanings may differ from those on another manufacturer's documents.

1. Absolute maximum ratings

The absolute maximum ratings are values that should never be exceeded, since doing so may result in deterioration of electrical characteristics or damage to the part itself as well as peripheral components.

1.1 Power supply voltage (V_{cc}/GND)

Expresses the maximum voltage that can be supplied between the positive and negative power supply terminals without causing deterioration of the electrical characteristics or destruction of the internal circuitry.

1.2 Differential input voltage (VID)

Indicates the maximum voltage that can be supplied between the non-inverting and inverting terminals without damaging the IC.

1.3 Input common-mode voltage range (VICR)

Signifies the maximum voltage that can be supplied to non-inverting and inverting terminals without causing deterioration of the electrical characteristics or damage to the IC itself. Normal operation is not guaranteed within the input common-mode voltage range of the maximum ratings – use within the input common-mode voltage range of the electric characteristics instead.

1.4 Operating temperature range and storage temperature range (T_{opr}, T_{stg})

The operating temperature range indicates the temperature range within which the IC can operate. The higher the ambient temperature, the lower the power consumption of the IC. The storage temperature range denotes the range of temperatures the IC can be stored under without causing excessive deterioration of the electrical characteristics.

1.5 Power dissipation (P_d)

Indicates the power that can be consumed by a particular mounted board at ambient temperature (25°C). For packaged products, P_d is determined by maximum junction temperature and the thermal resistance.

2. Electrical characteristics

2.1 Input offset voltage (V_{IO})

Signifies the voltage difference between the non-inverting and inverting terminals. It can be thought of as the input voltage difference required for setting the output voltage to 0V.

2.2 Input offset current (I_{IO})

Indicates the difference of the input bias current between the non-inverting and inverting terminals.

2.3 Input bias current (I_{IB})

Denotes the current that flows into or out of the input terminal, it is defined by the average of the input bias current at the non-inverting terminal and the input bias current at the inverting terminal.

2.4 Input common-mode voltage range (VICR)

Indicates the input voltage range under which the IC operates normally.

2.5 Large signal differential voltage gain (A_{VD})

The amplifying rate (gain) of the output voltage against the voltage difference between the non-inverting and inverting terminals, it is (normally) the amplifying rate (gain) with respect to DC voltage.

$A_{VD} = (\text{output voltage fluctuation}) / (\text{input offset fluctuation})$

2.6 Supply current (I_{CC})

Indicates the current of the IC itself that flows under specific conditions and during no-load steady state.

2.7 Low level output current (I_{OL})

Denotes the maximum current that can be output under specific output conditions.

2.8 Low level output voltage (V_{OL})

Signifies the voltage range that can be output under specific output conditions.

2.9 High level output current (I_{OH})

Indicates the current that flows into the IC under specific input and output conditions.

2.10 Response time (t_{re})

The interval between the application of input and output conditions.

2.11 Common-mode rejection ratio (CMRR)

Denotes the ratio of fluctuation of the input offset voltage when the in-phase input voltage is changed (DC fluctuation).

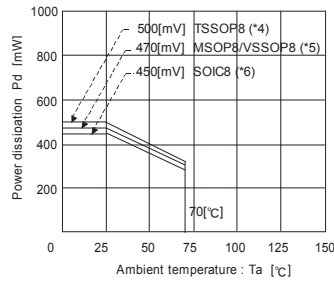
$CMRR = (\text{change of input common-mode voltage}) / (\text{input offset fluctuation})$

2.12 Power supply rejection ratio (PSRR)

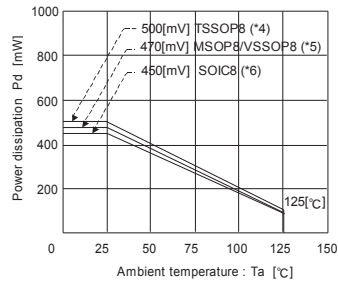
Signifies the ratio of fluctuation of the input offset voltage when the supply voltage is changed (DC fluctuation).

$PSRR = (\text{change in power supply voltage}) / (\text{input offset fluctuation})$

● Derating Curves



LM393DR/PWR/DGKR



LM2903DR/PWR/DGKR/VQDR/VQPWR

Power Dissipation

Package	Pd[W]	θ_{ja} [°C/W]
SOIC8 (*6)	450	3.6
TSSOP8 (*4)	500	4.0
MSOP8/VSSOP8 (*5)	470	3.76

$\theta_{ja} = (T_j - T_a) / P_d [°C/W]$

Fig.5 Derating Curves

● Precautions

1) Unused circuits

When there are unused circuits it is recommended that they be connected as in Fig. 6, setting the non-inverting input terminal to a potential within the in-phase input voltage range (VICR).

2) Input terminal voltage

Applying GND + 36V to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, irrespective of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.

3) Power supply (single / dual)

The op-amp operates when the specified voltage supplied is between Vcc and GND. Therefore, the single supply op-amp can be used as a dual supply op-amp as well.

4) Power dissipation Pd

Using the unit in excess of the rated power dissipation may cause deterioration in electrical characteristics due to a rise in chip temperature, including reduced current capability. Therefore, please take into consideration the power dissipation (Pd) under actual operating conditions and apply a sufficient margin in thermal design. Refer to the thermal derating curves for more information.

5) Short-circuit between pins and erroneous mounting

Incorrect mounting may damage the IC. In addition, the presence of foreign particles between the outputs, the output and the power supply, or the output and GND may result in IC destruction.

6) Terminal short-circuits

When the output and Vcc terminals are shorted, excessive output current may flow, resulting in undue heat generation and, subsequently, destruction.

7) Operation in a strong electromagnetic field

Operation in a strong electromagnetic field may cause malfunctions.

8) Radiation

This IC is not designed to withstand radiation.

9) IC handling

Applying mechanical stress to the IC by deflecting or bending the board may cause fluctuations in the electrical characteristics due to piezoelectric (piezo) effects.

10) Board inspection

Connecting a capacitor to a pin with low impedance may stress the IC. Therefore, discharging the capacitor after every process is recommended. In addition, when attaching and detaching the jig during the inspection phase, ensure that the power is turned OFF before inspection and removal. Furthermore, please take measures against ESD in the assembly process as well as during transportation and storage.

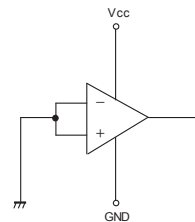


Fig.6 Disable circuit example

